

**R E M A R K S**

Claims 1, 3 - 6, 8 and 10 -15 are pending in this application, of which claims 10 - 15 have been withdrawn from consideration. By this Amendment, claims 1 and 8 have been amended and claims 7 and 9 have been canceled without prejudice or disclaimer. The applicant respectfully submits that no new matter has been added. It is believed that this Response is fully responsive to the Office Action dated December 5, 2002.

**35 U.S.C. §112, Second Paragraph, Rejection:**

In item 2 of the Office Action, claims 7 - 9 stand rejected under 35 U.S.C. §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

This rejection is respectfully traversed.

As indicated above, claims 7 and 9 have been canceled without prejudice or disclaimer and claim 8 has been amended to depend from claim 1. Thus, it is respectfully submitted that the rejection of claims 7 - 9 under 35 U.S.C. §112, second paragraph, is hereby moot. Accordingly, withdrawal of the rejection of claims 7 - 9 under 35 U.S.C. §112, second paragraph, is respectfully solicited.

**As To The Merits:**

As to the merits of this case, the Examiner sets forth the following rejection:

claims 1 - 6 stand rejected under 35 USC §102(b) as being anticipated by **Matsubara** (U.S. Patent No. 5,726,5010).

This rejection is respectfully traversed.

Claim 1, as amended, now calls for an insulated film disposed between the printed circuit board, not adhered thereto, and the electronic component so as to define a through hole for receiving the solder bump.

It is respectfully submitted that the amendments to claim 1 do not raise new issues nor require further consideration and/or search since claim 1 has been amended in the manner suggested by the examiner in the November 8, 2001 examiner initiated telephone call.

Moreover, it is respectfully submitted that **Matsubara** fails to disclose or fairly suggest an insulated film disposed between the printed circuit board, not adhered thereto, and the electronic component so as to define a through hole for receiving the solder bump.

Thus, it is respectfully asserted that the prior art fails to teach or suggest recitations of claims 1, 3 - 6 and 8 and requested that the Examiner allow claims 1, 3 - 6 and 8, along with the entire application, to issue. Accordingly, withdrawal of the rejection of claims 1, 3 - 6 and 8 under 35 U.S.C. §102(b) is respectfully solicited.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with Markings to Show Changes Made."

AMENDMENT

SERIAL NO. 09/536,993

If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, applicant respectfully petitions for an appropriate extension of time. The fees for such an extension or any other fees which may be due with respect to this paper, may be charged to Deposit Account No. 01-2340.

Respectfully submitted,

ARMSTRONG, WESTERMAN & HATTORI, LLP



Thomas E. Brown  
Attorney for Applicants  
Reg. No. 44,450

Atty. Docket No. 000296  
1725 K Street, N.W., Suite 1000  
Washington, DC 20006  
Tel.: (202) 659-2930  
Fax: (202) 887-0357  
TEB

**VERSION WITH MARKINGS TO SHOW CHANGES MADE****Serial No. 09/536,993****IN THE CLAIMS:**

Claims 7 and 9 have been canceled without prejudice or disclaimer.

Claims 1 and 8 have been amended as follows:

1. (Twice Amended) A printed circuit board unit comprising:

a printed circuit board;

an electronic component;

a solder bump interposed between the printed circuit board and the electronic component so as to fix the electronic component to the printed circuit board; and

an insulated film disposed between the printed circuit board, not adhered thereto, and the electronic component so as to define a through hole for receiving the solder bump, wherein the through hole is designed to form a constriction in the solder bump between the printed circuit board and the electronic component.

8. (Amended) The printed circuit board unit according to claim [7] 1, wherein an inner surface of the through hole is covered with a coating wet to the solder bump.